

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) ~~Apparatus~~ An apparatus for placing a semiconductor chip as a flipchip on a substrate, comprising

a flip device for flipping the semiconductor chip, the flip device being formed as a parallelogram construction ~~having consisting of~~ a support bracket, a first and a second swivel arm and a connecting arm and a ~~comprising~~ chip gripper arranged on the connecting arm, and a drive system for the back and forth movement of the parallelogram construction between a first limit position where the chip gripper accepts the semiconductor chip and a second limit position where the chip gripper places the semiconductor chip on the substrate.

2. (Currently amended) ~~Apparatus~~ The apparatus according to claim 1, wherein the parallelogram construction is arranged on a slide moveable in a vertical direction and ~~that~~ wherein the support bracket ~~can be turned~~ is turnable in relation to the slide on a vertical rotational axis.

3. (Currently amended) ~~Apparatus~~ The apparatus according to claim 1, wherein the first limit position and the second limit position of the parallelogram construction are defined mechanically by means of extended positions of the drive system.

4. (Currently amended) ~~Apparatus~~ The apparatus according to claim 2, wherein the first limit position and the second limit position of the parallelogram construction are defined mechanically by means of extended positions of the drive system.

5. (Currently amended) ~~Apparatus~~ The apparatus according to claim 1, wherein a force unit is arranged on the first swivel arm which serves to produce the force to be created between the semiconductor chip and the substrate when placing.
6. (Currently amended) ~~Apparatus~~ The apparatus according to claim 2, wherein a force unit is arranged on the first swivel arm which serves to produce the force to be created between the semiconductor chip and the substrate when placing.
7. (Currently amended) ~~Apparatus~~ The apparatus according to claim 3, wherein a force unit is arranged on the first swivel arm which serves to produce the force to be created between the semiconductor chip and the substrate when placing.
8. (Currently amended) ~~Apparatus~~ The apparatus according to claim 4, wherein a force unit is arranged on the first swivel arm which serves to produce the force to be created between the semiconductor chip and the substrate when placing.
9. (Currently amended) ~~Apparatus~~ The apparatus according to claim 5, wherein the force unit has a pressure cylinder to which a predetermined pressure can be applied which acts upon the chip gripper when placing the semiconductor chip on the substrate.
10. (Currently amended) ~~Apparatus~~ The apparatus according to claim 6, wherein the force unit has a pressure cylinder to which a predetermined pressure can be applied which acts upon the chip gripper when placing the semiconductor chip on the substrate.
11. (Currently amended) ~~Apparatus~~ The apparatus according to claim 7, wherein the force unit has a pressure cylinder to which a predetermined pressure can be applied which acts upon the

chip gripper when placing the semiconductor chip on the substrate.

12. (Currently amended) ~~Apparatus~~ The apparatus according to claim 8, wherein the force unit has a pressure cylinder to which a predetermined pressure can be applied which acts upon the chip gripper when placing the semiconductor chip on the substrate.

13. (Currently amended) ~~Apparatus~~ The apparatus according to claim 1, wherein the apparatus is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor ~~chips~~ chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.

14. (Currently amended) ~~Apparatus~~ The apparatus according to claim 2, wherein the apparatus is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor ~~chips~~ chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.

15. (Currently amended) ~~Apparatus~~ The apparatus according to claim 3, wherein the apparatus is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor ~~chips~~ chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.

16. (Currently amended) ~~Apparatus~~ The apparatus according to claim 4, wherein the apparatus is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor ~~chips~~ chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.

17. (Currently amended) ~~Apparatus~~ The apparatus according to claim 5, wherein the apparatus is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor ~~chips~~ chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.

18. (Currently amended) ~~Apparatus~~ The apparatus according to claim 6, wherein the apparatus

is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor chips chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.

19. (Currently amended) ~~Apparatus~~ The apparatus according to claim 7, wherein the apparatus is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor chips chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.

20. (Currently amended) ~~Apparatus~~ The apparatus according to claim 8, wherein the apparatus is a die bonder comprising a pick and place system which picks ~~the~~ a semiconductor chips chip from a wafer table and delivers ~~them~~ the semiconductor chip to the flip device.